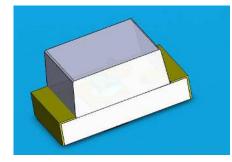


DATASHEET

SMD • B EAST1608BA1



Features

- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Mono-color type.
- Pb-free.
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm).

Description

- The SMD LED is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

Applications

- Backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.

Device Selection Guide

Chip Materials	Emitted Color		Resin Color	
InGaN	Blue		Water Clear	
Absolute Maximum Ra	tings (Ta=25℃)			
Parameter	Symbol	Rating	Unit	

Reverse Voltage	V _R	5	V
Forward Current	I _F	20	mA
eak Forward Current (Duty 1/10 @1KHz)	I _{FP}	100	mA
Power Dissipation	Pd	95	mW
Electrostatic Discharge	ESD _{HBM}	150	V
Operating Temperature	T _{opr}	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +90	°C
Soldering Temperature	Tsol	Reflow Soldering : 260 $^\circ\!\mathbb{C}$ for 10 sec. Hand Soldering : 350 $^\circ\!\mathbb{C}$ for 3 sec.	

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	lv	45.0		112.0	mcd	
Viewing Angle	20 _{1/2}		100		deg	
Peak Wavelength	λр		468		nm	_
Dominant Wavelength	λd	464.5		476.5	nm	[—] I _F =20mA
Spectrum Radiation Bandwidth	Δλ		25		nm	
Forward Voltage	V _F	2.70	3.30	3.70	V	
Reverse Current	I _R			50	μΑ	V _R =5V

Note:

1.Tolerance of Luminous Intensity: ±11%

2. Tolerance of Dominant Wavelength ±1nm

Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
P1	45.0	57.0		
P2	57.0	72.0		
Q1	72.0	90.0	mcd	I _F =20mA
Q2	90.0	112.0		

Bin Range Of Dom. Wavelength

Bin Code	Min.	Max.	Unit	Condition
A9	464.5	467.5		
A10	467.5	470.5		
A11	470.5	473.5	nm	I _F =20mA
A12	473.5	476.5		

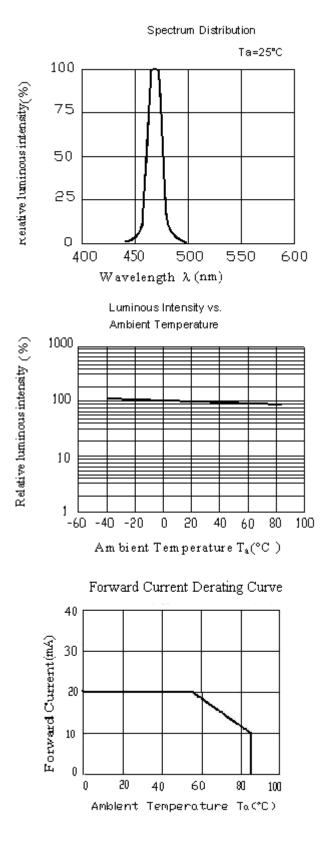
Note:

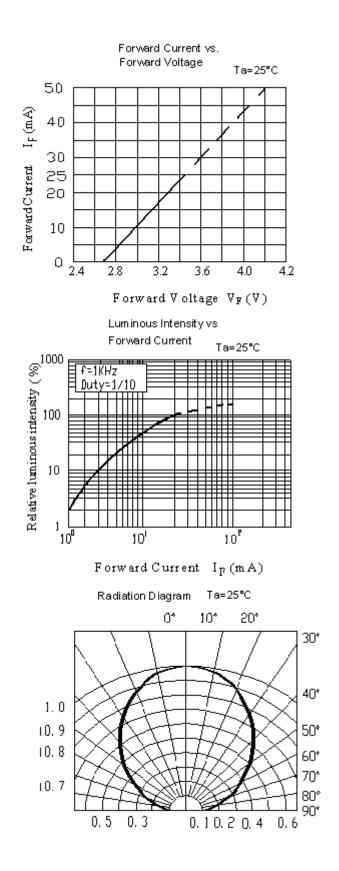
1.Tolerance of Luminous Intensity: ±11%

2. Tolerance of Dominant Wavelength ±1nm

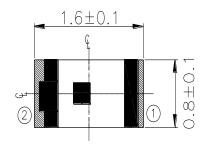
DATASHEET SMD • B EAST1608BA1

Typical Electro-Optical Characteristics Curves



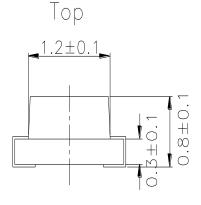


Package Dimension



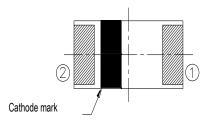


Polarity



Side

Recommend Sodering Pad



2 0.5±0.2

Bottom

Suggested pad dimension is just for reference only. Please modify the pad dimension based on individual need.



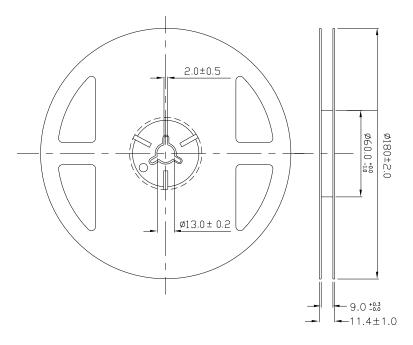


Label Explanation



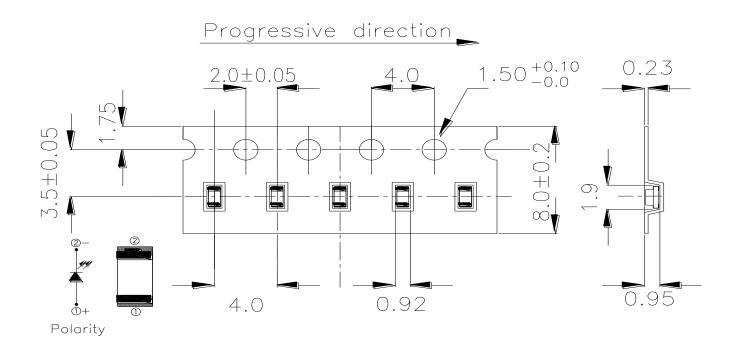
- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Chromaticity Coordinates & Dom. Wavelength Rank
- REF: Forward Voltage Rank
- · LOT No: Lot Number

Reel Dimensions



Note: The tolerances unless mentioned is $\pm 0.1 \text{mm}$,Unit = mm

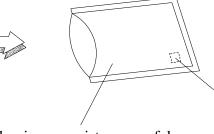
Carrier Tape Dimensions: Loaded quantity 3000 PCS per reel

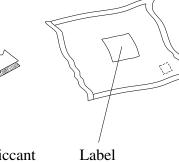


Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

Moisture Resistant Packaging







Label

Aluminum moisture-proof bag

Desiccant



Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big

current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package: The LEDs should be kept at 30° C or less and 90%RH or less.

2.3 After opening the package: The LED's floor life is 1 year under 30°C or less and 60% RH or less.

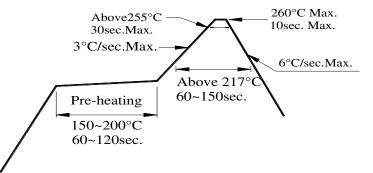
If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : $60\pm5^{\circ}$ C for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

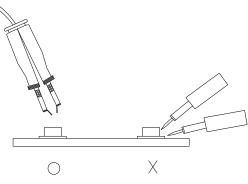
3.4 After soldering, do not warp the circuit board.

4.Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350° for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.





Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight Americas before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.